In-Process Cutting Temperature Monitoring Method Based on Impedance Model of **Dielectric Coating Layer at Tool-Chip Interface** Journal of Ā M Heebum Chun | William Park '23 | Jungsub Kim, Ph.D. | ChaBum Lee, Ph.D.



Manufacturing and Materials Processing

- manufacturing efficiency.
- challenging due to the physical inaccessibility.
- dielectric material.





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Veteran Research







Turning machining experimental setup for impedance measurement and results

Conclusion

- method was introduced
- dependent on temperature
- monitoring the machining process
- monitoring method

Future Works

- characterizing the impedance model.





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Machining Experiment

Impedance at the TCI dropped drastically as machining started during facing operations and showed different temperature profiles for turning

Facing machining experimental setup for impedance measurement and results

Preliminary study of the impedance model based in-process machining process monitoring

Impedance spectroscopy showed that the impedance of the dielectric coating layer was

Machining experiments were conducted, and the method exhibited the capability of

• Impedance of the dielectric layer was also dependent on the contact area

Preliminary study results showed that the method can be applied to the machining process

Relationship among impedance, temperature, contact area will be numerically and quantitatively analyzed throughout calibrations and characterization process

· Various cutting mechanics and machining processes will be assessed and monitored Other dielectric coating materials and different workpiece materials will also be considered after



